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Texas Instruments
CDC2351DBR

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Datasheet of CDC2351DBR - IC CLK BUFFER 1:10 100MHZ 24SSOP

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## CDC2351 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

SCAS442D - FEBRUARY 1994 - REVISED SEPTEMBER 2000

 Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications

- Operates at 3.3-V V<sub>CC</sub>
- LVTTL-Compatible Inputs and Outputs
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Distributes One Clock Input to Ten Outputs
- Outputs Have Internal Series Damping Resistor to Reduce Transmission Line Effects
- Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages
- Available in Q-Temp Automotive
   High Reliability Automotive Applications
   Configuration Control / Print Support
   Qualification to Automotive Standards

	(TOP VIEW)										
GND [ Y10 [	2	U	24 23	GND Y1							
V <sub>CC</sub> [ Y9 [	4		22 21	] V <sub>CC</sub> ] Y2							
OE [			20	GND							
Α[	6		19	] Y3							
P0 [	7		18	] Y4							
P1 [	8		17	GND							
Y8 [	9		16	] Y5							
V <sub>CC</sub> [ Y7 [	10		15	] v <sub>cc</sub>							
Y7 [	11		14	] Y6							
GND [	12		13	GND							

**DB OR DW PACKAGE** 

#### description

The CDC2351 is a high-performance clock-driver circuit that distributes one input (A) to ten outputs (Y) with minimum skew for clock distribution. The output-enable ( $\overline{OE}$ ) input disables the outputs to a high-impedance state. Each output has an internal series damping resistor to improve signal integrity at the load. The CDC2351 operates at nominal 3.3-V  $V_{CC}$ .

The propagation delays are adjusted at the factory using the P0 and P1 pins. The factory adjustments ensure that the part-to-part skew is minimized and is kept within a specified window. Pins P0 and P1 are not intended for customer use and should be connected to GND.

The CDC2351 is characterized for operation from  $0^{\circ}$ C to  $70^{\circ}$ C. The CDC2351Q is characterized for operation over the full automotive temperature range of  $-40^{\circ}$ C to  $125^{\circ}$ C.

#### **FUNCTION TABLE**

INP	UTS	OUTPUTS
Α	OE	In
L	Н	Z
Н	Н	Z
L	L	L
Н	L	Н



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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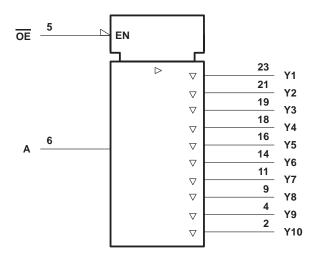
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### CDC2351

## 1-LINE TO 10-LINE CLOCK DRIVER

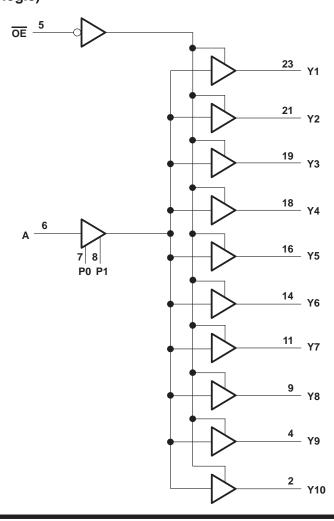
WITH 3-STATE OUTPUTS
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## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)







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## CDC2351 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Overally walks are asset of M	0 5 1/4- 4 0 1/
Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high state or power-off state,	
V <sub>O</sub> (see Note 1)	$\dots \dots -0.5 \text{ V to } 3.6 \text{ V}$
Current into any output in the low state, I <sub>O</sub>	24 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>I</sub> < 0)	50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DB package	0.65 W
DW package	1.7 W
Storage temperature range, T <sub>stg</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

#### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage	3	3.6	V	
VIH	High-level input voltage		2		V
$V_{IL}$	Low-level input voltage		0.8	V	
VI	Input voltage				V
IOH	High-level output current			-12	mA
loL	Low-level output current			12	mA
fclock	Input clock frequency				MHz
T. Operating free air temperature		CDC2351	0	70	°C
TA	Operating free-air temperature	CDC2351Q	-40	125	C

NOTE 3: Unused pins (input or I/O) must be held high or low.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	TYP	MAX	UNIT		
VIK	V <sub>CC</sub> = 3 V,	I <sub>I</sub> = -18 mA				-1.2	V
Voн	$V_{CC} = 3 V$ ,	I <sub>OH</sub> = – 12 mA		2			V
VOL	$V_{CC} = 3 V$ ,	I <sub>OL</sub> = 12 mA				0.8	V
lį	V <sub>CC</sub> = 3.6 V,	$V_I = V_{CC}$ or GND				±1	μΑ
1 <sub>0</sub> ‡	V <sub>CC</sub> = 3.6 V,	V <sub>O</sub> = 2.5 V	-7		-70	mA	
loz	V <sub>CC</sub> = 3.6 V,	V <sub>CC</sub> = 3 V or 0				±10	μΑ
			Outputs high			0.3	
ICC	$V_{CC} = 3.6 \text{ V},$	$I_O = 0$ , $V_I = V_{CC}$ or GND	Outputs low			15	mA
			Outputs disabled			0.3	
C <sub>i</sub>	$V_I = V_{CC}$ or GND,	V <sub>CC</sub> = 3.3 V,	f = 10 MHz		4		pF
Co	$V_O = V_{CC}$ or GND,	$V_{CC} = 3.3 \text{ V},$	f = 10 MHz		6		pF

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.



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## CDC2351 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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## switching characteristics, C<sub>L</sub> = 50 pF (see Figures 1 and 2)

			С	DC2351		CDC2	351Q	CDC	2351	
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub>	V <sub>CC</sub> = 3.3 V, T <sub>A</sub> = 25°C			to 3.6 V, to 125°C	V <sub>CC</sub> = 3 V T <sub>A</sub> = 0°C	UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	А	Y	3.8	4.3	4.8	1.1	11			ns
<sup>t</sup> PHL	^	Y	3.6	4.1	4.6	1	9.7			115
<sup>t</sup> PZH	ŌĒ	Y	2.4	4.9	6.0	1	12	1.8	6.9	ns
t <sub>PZL</sub>	OE	Y	2.4	4.3	6.0	1	11.1	1.8	6.9	115
t <sub>PHZ</sub>	ŌĒ	Υ	2.2	4.4	6.3	1	11.1	2.1	7.1	ns
t <sub>PLZ</sub>	OE	T T	2.2	4.6	6.3	1	11.5	2.1	7.3	115
tsk(o)	Α	Y		0.3	0.5		2.5		0.5	ns
<sup>t</sup> sk(p)	А	Y		0.2	0.8		3		0.8	ns
tsk(pr)	А	Y			1				1	ns
t <sub>r</sub>	А	Υ					2.5		2.5	ns
t <sub>f</sub>	А	Υ					2.5		2.5	ns

# switching characteristics temperature and $V_{\hbox{CC}}$ coefficients over recommended operating free-air temperature and $V_{\hbox{CC}}$ range (see Note 4)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN MAX	UNIT
∝t <sub>PLH</sub> (T)	Average temperature coefficient of low to high propagation delay	Α	Y	85†	ps/10°C
∝t <sub>PHL</sub> (T)	Average temperature coefficient of high to low propagation delay	Α	Υ	50†	ps/10°C
∝t <sub>PLH</sub> (V <sub>CC</sub> )	Average V <sub>CC</sub> coefficient of low to high propagation delay	А	Y	-145 <sup>‡</sup>	ps/ 100 mV
∝t <sub>PHL</sub> (V <sub>CC</sub> )	Average V <sub>CC</sub> coefficient of high to low propagation delay	А	Y	-100‡	ps/ 100 mV

<sup>† ∝</sup>tpLH(T) and ∝tpHL(T) are virtually independent of VCC.

‡ of the thick of

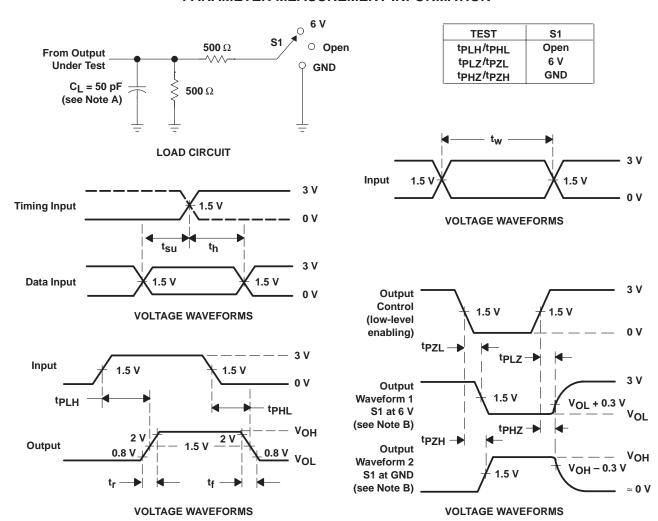


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CDC2351 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{\Omega}$  = 50  $\Omega$ ,  $t_{\Gamma} \leq$  2.5 ns,  $t_{\Gamma} \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



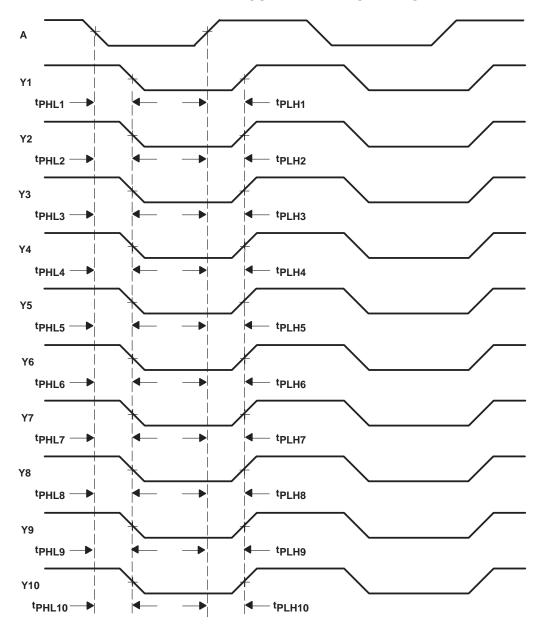
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#### CDC2351

# 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. Output skew,  $t_{Sk(0)}$ , is calculated as the greater of:

- The difference between the fastest and slowest of tpLHn (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
- The difference between the fastest and slowest of  $t_{PHLn}$  (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
- B. Pulse skew,  $t_{SK(p)}$ , is calculated as the greater of  $|t_{PLHn} t_{PHLn}|$  (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10).
- C. Process skew,  $t_{sk(pr)}$ , is calculated as the greater of:
  - The difference between the fastest and slowest of tp<sub>LHn</sub> (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions
  - The difference between the fastest and slowest of tpHLn (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of  $t_{sk(p)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$ 





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PACKAGE OPTION ADDENDUM

11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish		Op Temp (°C)	Top-Side Markings	Samples
CDC2351DB	ACTIVE	SSOP	DB	24	60	(2) Green (RoHS & no Sb/Br)	CU NIPDAU	(3) Level-1-260C-UNLIM	0 to 70	(4) CK2351	Samples
CDC2351DBG4	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351	Samples
CDC2351DBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI	0 to 70		
CDC2351DBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351	Samples
CDC2351DBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351	Samples
CDC2351DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351	Samples
CDC2351DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351	Samples
CDC2351DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351	Samples
CDC2351DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351	Samples
CDC2351PWR	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI			
CDC2351PWRG4	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI			
CDC2351QDB	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q	Samples
CDC2351QDBG4	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q	Samples
CDC2351QDBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q	Samples
CDC2351QDBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



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PACKAGE OPTION ADDENDUM

11-Apr-2013

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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#### OTHER QUALIFIED VERSIONS OF CDC2351:

● Enhanced Product: CDC2351-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

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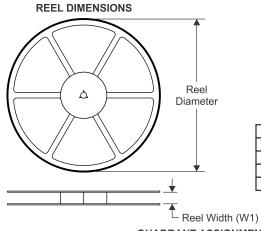
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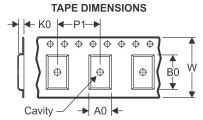


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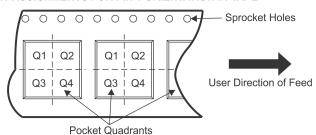
#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2351DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CDC2351DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CDC2351QDBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CDC2351QDBRG4	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1

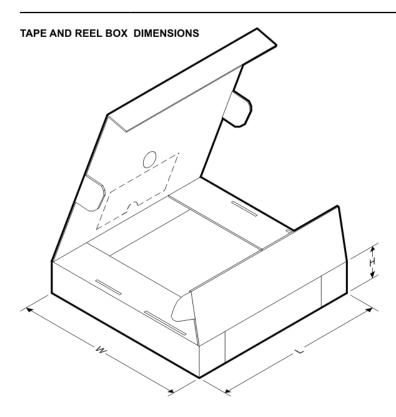
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#### \*All dimensions are nominal

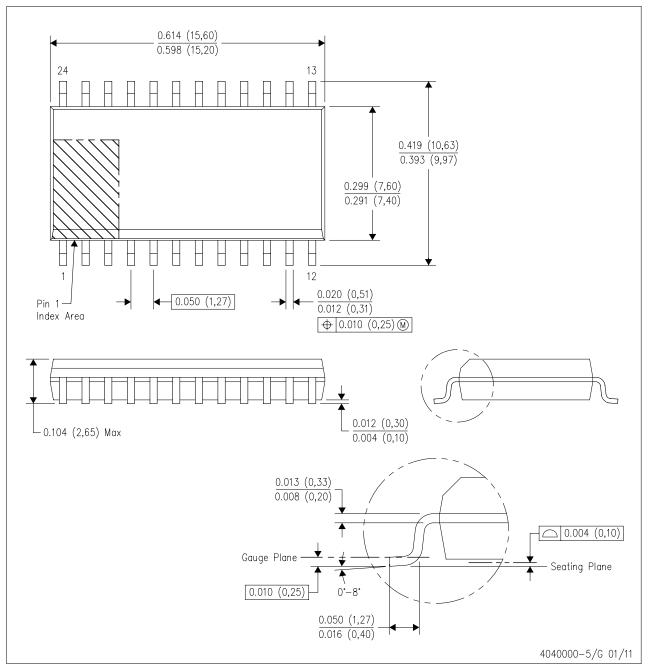
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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC2351DBR	SSOP	DB	24	2000	367.0	367.0	38.0
CDC2351DWR	SOIC	DW	24	2000	367.0	367.0	45.0
CDC2351QDBR	SSOP	DB	24	2000	367.0	367.0	38.0
CDC2351QDBRG4	SSOP	DB	24	2000	367.0	367.0	38.0



## **MECHANICAL DATA**

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M—1994.

- 3. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.

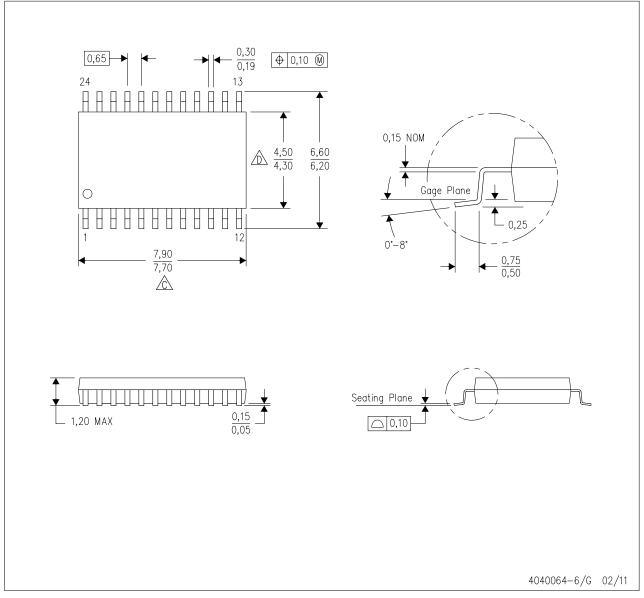




## **MECHANICAL DATA**

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153





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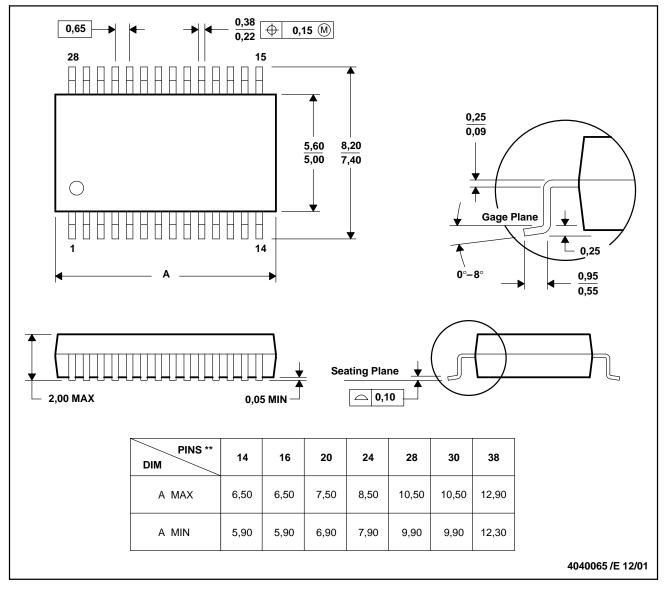
### **MECHANICAL DATA**

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

#### DB (R-PDSO-G\*\*)

#### 28 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150





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